

IN THE SPECIFICATION:

Please amend the specification of the above-referenced application to appear as below. Such amendments are requested merely to modify typographical errors in the specification and do not add any new matter to the specification.

Please replace the first full paragraph on page 3 with the following:

"The present invention recognizes and addresses various of the foregoing limitations and drawbacks, and others, concerning the lack of a surface mount multi-layer ceramic capacitor (MLC) device for low inductance decoupling applications. Therefore, the present invention provides an MLC device, generally square in configuration, for decoupling high frequency transients, in which the device has a first terminal substantially located around the entire periphery of the device and a second opposing polarity terminal located by way of a through-via in generally the middle of the device body."

a1 [ Please replace the second full paragraph on page 3 with the following: ]

"It is, therefore, a principle object of the subject invention to provide an MLC device. More specifically, it is an object of the present device to provide an MLC device which exhibits a low inherent inductance. Most specifically, it is an object of the present invention to provide an MLC device with low inductance characteristics and a high capacitance/area which is readily adaptable to variation in size and dimension yet simple to manufacture and cost effective."

Please replace the second full paragraph on page 5 with the following:

a2 "In one exemplary embodiment, a square capacitor device is provided having a ceramic body formed from a plurality of ceramic-electrode layers interleaved to form a stack. The stack is pressed and sintered to achieve a substantially unitary capacitor body. A first polarity terminal is located substantially about the entire periphery of the device body. A

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Cont

second polarity terminal is formed by a through-via located generally in the middle of the device body. The through-via may or may not be filled with solder."

Please replace the first full paragraph in the DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS Section on page 7 with the following:

a3

"Reference will now be made in detail to presently preferred embodiments of the invention, examples of which are fully represented in the accompanying drawings. Such examples are provided by way of an explanation of the invention, not limitation thereof. In fact, it will be apparent to those skilled in the art that various modifications and variations can be made in the present invention, without departing from the spirit and scope thereof. For instance, features illustrated or described as part of one embodiment can be used on another embodiment to yield a still further embodiment. Still further, variations in selection of materials and/or characteristics may be practiced to satisfy particular desired user criteria. Thus, it is intended that the present invention cover such modifications and variations as come within the scope of the present features and their equivalents."

Please replace the last full paragraph on page 8 (continuing to page 9) with the following:

a4

"As seen in Figure 3B, the second ceramic-electrode layer includes a second electrode plate 24 that extends to via 22 for making electrical connection with terminal 16. A perimeter region 26 of the ceramic sheet is left uncovered by second electrode plate 24 to prevent electrical connection between second electrode plate 24 and terminal 14."

Please replace the first full paragraph on page 10 with the following:

a5

"As seen in Figure 7B, the second ceramic-electrode layer includes a second electrode plate 32 covering substantially the entire underlying electrode sheet. A circular portion 34 of the sheet surrounding through-via terminals 38 is left uncovered so as to